

Search Notes

Application/Control No.

10/693,896

Examiner

Stephen W. Smoot

Applicant(s)/Patent under
Reexamination

CHEN ET AL.

Art Unit

2813

SEARCHED

Class	Subclass	Date	Examiner
438	108	1/27/2005	SWS
438	612	1/27/2005	SWS
438	613	1/27/2005	SWS
438	614	1/27/2005	SWS
257	738	1/27/2005	SWS
257	E21.508	1/27/2005	SWS
29	842	1/27/2005	SWS

*S.W.S.***INTERFERENCE SEARCHED**

Class	Subclass	Date	Examiner

**SEARCH NOTES
(INCLUDING SEARCH STRATEGY)**

	DATE	EXMR
Key Words: Solder Ball, Bump - Flux; Active Surface; Bond Pad; Under Bump Metallurgy;	1/27/2005	<i>S.W.S.</i> SWS
Passivation Layer; Solder Reflow; Solid Flux.	1/27/2005	<i>S.W.S.</i> SWS
Search Tools - EAST (attached): USPAT; US PG PUBS; Derwent; EPO; JPO; IBM TDB	1/27/2005	<i>S.W.S.</i> SWS